	Application No.	Applicant(s)	V
	10/087,191	JAEGER, RICHARD E.	
Notice of Allowability	Examiner	Art Unit	
	Satya B Sastri	1713	
The MAILING DATE of this communication apper claims being allowable, PROSECUTION ON THE MERITS IS of the previously mailed), a Notice of Allowance (PTOL-85) DTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHT OF The provious of the applicant. See 37 CFR 1.313	or other appropriate comm GHTS. This application is and MPEP 1308.	unication will be mailed in due course	e. THIS e initiativ
This communication is responsive to <u>amendment filed on J</u>	<u>anuary 15, 2004</u> .		
The allowed claim(s) is/are 1,2,4-6 and 8-44.			
☐ The drawings filed on are accepted by the Examine	r.		
 Acknowledgment is made of a claim for foreign priority ur a) ☐ All b) ☐ Some* c) ☐ None of the: 1. ☐ Certified copies of the priority documents have 2. ☐ Certified copies of the priority documents have 	e been received.	on No	
2. ☐ Certified copies of the priority documents have3. ☐ Copies of the certified copies of the priority do	cuments have been receive	ed in this national stage application fr	om the
International Bureau (PCT Rule 17.2(a)).			
* Certified copies not received:			
Applicant has THREE MONTHS FROM THE "MAILING DATE" noted below. Failure to timely comply will result in ABANDONN THIS THREE-MONTH PERIOD IS NOT EXTENDABLE. . A SUBSTITUTE OATH OR DECLARATION must be subnitive to the period of the period	nitted. Note the attached E	XAMINER'S AMENDMENT or NOTIC	
A SUBSTITUTE OATH OR DECLARATION must be subti INFORMAL PATENT APPLICATION (PTO-152) which giv	res reason(s) why the oath	or declaration is deficient.	
. CORRECTED DRAWINGS (as "replacement sheets") mu	st be submitted.		
(a) ☐ including changes required by the Notice of Draftsper	son's Patent Drawing Revi	ew (PTO-948) attached	
1) Decreto or 2) D to Paper No./Mail Date	_•		
(b) ☐ including changes required by the attached Examiner Paper No./Mail Date			k) of
Paper No./Mail Date Identifying indicia such as the application number (see 37 CFR each sheet. Replacement sheet(s) should be labeled as such in	the mean are a		
 DEPOSIT OF and/or INFORMATION about the dep attached Examiner's comment regarding REQUIREMENT 	acit of BIOLOGICAL MA	TERIAL must be submitted. Note	the
Attachment(s) 1. ☐ Notice of References Cited (PTO-892) 2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948) 3. ☑ Information Disclosure Statements (PTO-1449 or PTO/SE Paper No./Mail Date) 6. ☐ Interview Paper N 3/08), 7. ☐ Examine	i Informal Patent Application (PTO-15 v Summary (PTO-413), lo./Mail Date r's Amendment/Comment er's Statement of Reasons for Allowar	

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DETAILED ACTION

1. This office action is in response to the amendment filed on January 15, 2004. With the addition of new *claims 43 and 44* and cancellation of *claims 3 and 7, claims 1, 2, 4-6, 8-44 are now pending in the application*. In view of the amendment, rejection of *claims 38 and 39* under 35 U.S.C. 103 is withdrawn, rejection of *claims 1-23, 26-39, 4, 42* 35 U.S.C. 103(a) as being unpatentable over Dershem et al. (US 5,232,962) in view of Dershem et al. (US 6,034,194) is withdrawn, rejection of *claims 24, 25* are rejected under 35 U.S.C. 103(a) as being unpatentable over Dershem et al. (US 5,232,962) in view of Dershem et al. (US 6,034,194) and Dershem et al. (US 5,717,034) is withdrawn and rejection of *claims 1-6, 12-20, 8-39, 41, 42* under 35 U.S.C. 102(b) as being anticipated by, or in the alternative, under 35 U.S.C. 103(a) as obvious over Dershem et al. (US 5,717,034) is also withdrawn.

Allowable Subject Matter

- 2. *Claims 1, 2, 4-6, 8-44* are allowed.
- 3. The following is an examiner's statement of reasons for allowance:

The present claims are allowable over the closest reference: Dershem et al. (US 5,232,962) and Dershem et al. (US 6,034,194).

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The present invention discloses an adhesive composition comprising at least one maleimide-containing monomer, optionally at least one cure initiator, and a plurality of spacers constructed from one or more organic polymers (*claim 1*).

The prior art to Dershem et al. ('962) is in regard to adhesive composition with bond line limiting spacer having a hardenable adhesive component and a plurality of spacers, the bond line thickness being maintained at a selected limit by the spacer elements. The disclosure further includes that the adhesive vehicle and spacer elements may be formed from many different materials depending on the nature of the materials to be bonded and the bonding composition itself. An example of the adhesive vehicle includes an epoxy resin. The spacer element may be collapsible and based on organic polymers such as collapsible spheroids made from polypropylene carbonate and polyalkyl methacrylate resins. The plastics determined to be useful as collapsible spacer elements may be non-charring, depolymerizable polymers having relatively low softening point, between 35-105°C. Working example 1 includes polyisobutyl methacrylate particles which are spherical in shape and classified to a mesh size of -100 to +200 mesh. A semiconductor die-attach bonding composition comprising adhesive paste composition may be used in bonding a pair of surfaces in a semiconductor device.

The prior art to Dershem et al. ('034) discloses adhesive formulations comprising perflourinated hydrocarbon polymers as fillers, a curing catalyst and optionally other additives such as coupling agents, additional fillers etc. Monomer vehicles for use in the composition may be based on maleimides, (meth)acrylates, propargyl ether materials, silicone based adhesive formulations etc. The polymer particle is further characterized as having a particle size in the

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range of about 0.1 up to about $100 \mu m$. The method of adhesively attaching a microelectronic device to a substrate, assemblies comprising cured adhesive and a variety of substrates are disclosed.

Neither prior art teaches a combination of a maleimide-based adhesive composition and a plurality of spacers constructed from one or more organic polymers as disclosed in the instant invention. Therefore, the instantly claimed invention is deemed allowable over the closest prior art of record as per said art neither anticipating nor rendering obvious the instantly claimed adhesive composition comprising at least one maleimide-containing monomer, optionally at least one cure initiator, and a plurality of spacers constructed from one or more organic polymers.

There is no teaching or suggestion or motivation to modify the prior art compositions so as to deduce the instantly claimed adhesive composition of the present invention.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Satya Sastri at (571) 272-1112.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David Wu can be reached at (571) 272-1114.

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Any inquiry of a general nature or relating to the status of this application should be directed to the group receptionist at (703) 308-0661.

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February 9, 2004

DAVID W. WU SUPERVISORY PATENT EXAMINER TECHNOLOGY CENTER 1700